Effective March 1998

YES

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

Rev. 1-10-03

Japan

(X) Origin	al ()	Supplemental	() Substitute	() PCT	() DESIGN
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As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

for patent or inventor's certificate lisa filing date before that of the applic		ow any application for patent or invi	entor's certificate having
hereby claim priority benefits under	Title 35, United States Code, §119 (and	1 §172 if this application is for a Desi	ion) of any application(s
I acknowledge my duty to disclose defined in Title 37, Code of Federal	to the Patent and Trademark Office all Regulations, §1.56.	information known to me to be ma	aterial to patentability a
I hereby state that I have reviewed as any amendment(s) referred to above	nd understand the content of the above-	identified specification, including th	ne claims, as amended b
or () the specification in International A	Application No., filed, and as amended	d on _(if applicable).	
(X) the specification in application S	Serial No.	, filed October 28, 2003, and with	amendments through
() the attached specification, or			
of which is described and claimed in	1:		
ELECTRONIC COMPONENT-	MOUNTED COMPLETED PRODU	CT	-
PRODUCT WITH THE ELEC	TRONIC COMPONENT-MOUNTE	D COMPONENT, AND	
			_
	FOR ELECTRONIC COMPONEN		_

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

2002-316022

October 30, 2002

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents

associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from <u>AOYAMA & PARTNERS</u> as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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Post Office Address	ADDRESS	СІТУ	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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5th Inventor	Date
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The above application may be more particularly identified as follow	ws:
U.S. Application Serial No. 10/694,347 Filing	Date October 28, 2003
Applicant Reference Number 538578 Atty Docket No. 2003 151	7A

Title of Invention MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPONENT, MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT WITH THE ELECTRONIC COMPONENT-MOUNTED COMPONENT, AND ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT